

Appl. No. 10/692,174  
Suppl Amdt. dated January 13, 2006

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application.

**Listing of Claims:**

Claims 1-25 (canceled)

Claim 26 (Currently amended): A test apparatus for testing an electronic device, said apparatus comprising:

a substrate; and

a plurality of probes, each said probe ~~comprising palladium and further~~ comprising:

a contact tip disposed to make a temporary, pressure based connection

with a terminal of said electronic device during testing of said electronic device;

a base secured to said substrate; and

a body disposed at least in part away from said substrate and configured to

flex and exert a counter force while said contact tip is pressed against said

terminal of said electronic device,

wherein said body is attached to said base and said tip is attached to said body,

said tip comprises substantially palladium or a palladium alloy, and

said body comprises substantially a spring material that does not comprise a substantial amount of palladium.

Claim 27-31 (Canceled)

Claim 32 (Currently amended): The test apparatus of claim 26, wherein said tip comprises substantially a palladium cobalt alloy.

Claim 33 (Previously presented): The test apparatus of claim 26, wherein said tip is integrally formed with said body.

Claim 34 (Canceled)

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Claim 35 (Withdrawn): The test apparatus of claim 26, wherein said base and said body are integrally formed.

Claim 36 (Previously presented): The test apparatus of claim 26, wherein said body comprises a beam that is structurally distinct from said base.

Claim 37-40 (Canceled)

Claim 41 (Previously presented): The test apparatus of claim 26, wherein said test apparatus is a probe card assembly.

Claim 42 (Currently amended): A test apparatus for testing an electronic device, said test apparatus comprising:

a substrate; and

a plurality of probes attached to said substrate, ~~[[and]]~~ each said probe comprising:

a contact ~~[[tips]]~~ tip disposed to make a temporary, pressure based connections with terminals electrical connection with a terminal of said electronic device to be tested, wherein ~~[[each]]~~ said probe contact tip comprises substantially palladium or a palladium alloy, and

a spring-like body configured to flex and exert a counter force in response to said contact tip being pressed against said terminal of said electronic device, wherein said body comprises a resilient material and does not comprise a substantial amount of palladium.

Claim 43 (Currently amended): The test apparatus of claim 42, wherein each said ~~probe~~ contact tip comprises substantially a palladium cobalt alloy.

Claims 44-47 (Canceled)

Claim 48 (Previously presented): The test apparatus of claim 42, wherein said test apparatus is a probe card assembly.

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**Claims 49-72 (Canceled)**

**Claim 73 (Previously presented):** The test apparatus of claim 26, wherein said body and said base are distinct structures.

**Claim 74 (Previously presented):** The test apparatus of claim 26, wherein said body and said tip are distinct structures.

**Claim 75 (Previously presented):** The test apparatus of claim 74, wherein said body and said base are distinct structures.

**Claim 76 (Previously presented):** The test apparatus of claim 26, wherein each probe is configured to contact one of said terminals of said electronic device such that no two probes contact a same terminal of said electronic device.

**Claim 77 (Previously presented):** The test apparatus of claim 76, wherein said base is attached to said body at a first end of said body and said tip is attached to said body at a second end of said body, and said second end of said body is moveable such that said second end of said body deflects upon contact with a terminal of said electronic device.

**Claim 78 (Previously presented):** The test apparatus of claim 26, wherein said palladium is electroplated.

**Claim 79 (Currently amended):** The test apparatus of claim 42, wherein each said probe further comprises a post attached to a terminal on said substrate ~~and a body~~, said body connecting said post and said tip.

**Claim 80 (Previously presented):** The test apparatus of claim 79, wherein said post and said body are distinct structures attached one to another.

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Claim 81 (Previously presented): The test apparatus of claim 80, wherein said tip and said body are distinct structures attached to one another.

Claim 82 (Previously presented): The test apparatus of claim 79, wherein said tip and said body are distinct structures attached to one another.

Claim 83 (Previously presented): The test apparatus of claim 79, wherein each probe is configured to contact one of said terminals of said electronic device such that no two probes contact a same terminal of said electronic device.

Claim 84 (Previously presented): The test apparatus of claim 79, wherein said post is attached to said body at a first end of said body and said tip is attached to said body at a second end of said body, and said second end of said body is moveable such that said second end of said body deflects upon contact with a terminal of said electronic device.

Claim 85 (Previously presented): The test apparatus of claim 42, wherein said palladium is electroplated.

Claim 86 (Canceled)

Claim 87 (Currently amended): The test apparatus of claim 26, wherein said contact tips of said probes are disposed to contact terminals of said electronic device having a pitch of less than five mils spacing between adjacent ones of said terminals.

Claim 88 (Currently amended): The test apparatus of claim 26, wherein said electronic device comprises a semiconductor die, and said contact tips of said probes are disposed to make temporary contact with a plurality of terminals of said semiconductor die.

Claim 89 (Previously presented): The test apparatus of claim 88, wherein said tips are disposed to make temporary contact simultaneously with a plurality of terminals of a plurality of semiconductor dies.

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Claim 90 (Previously presented): The test apparatus of claim 89, wherein said plurality of dies compose an unsingulated semiconductor wafer.

Claim 91 (Previously presented): The test apparatus of claim 88, wherein said terminals are bond pads of said semiconductor die.

Claim 92 (Previously presented): The test apparatus of claim 26, wherein said terminal is flat.

Claim 93 (Currently amended): The test apparatus of claim 43, wherein said contact tips of said probes are disposed to contact terminals of said electronic device having a pitch of less than five mils spacing between adjacent ones of said terminals.

Claim 94 (Currently amended): The test apparatus of claim 42, wherein said contact tips of said probes are disposed to contact terminals of said electronic device having a pitch of less than five mils spacing between adjacent ones of said terminals.

Claim 95 (Currently amended): The test apparatus of claim 42, wherein said electronic device comprises a semiconductor die, and said contact tips of said probes are disposed to make temporary contact with a plurality of terminals of said semiconductor die.

Claim 96 (Previously presented): The test apparatus of claim 95, wherein said tips are disposed to make temporary contact simultaneously with a plurality of terminals of a plurality of semiconductor dies.

Claim 97 (Previously presented): The test apparatus of claim 96, wherein said plurality of dies compose an unsingulated semiconductor wafer.

Claim 98 (Previously presented): The test apparatus of claim 95, wherein said terminals are bond pads of said semiconductor die.

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**Claim 99 (Previously presented):** The test apparatus of claim 42, wherein said terminal is flat.